Advanced Solution for Vertical-in-Line Equipment | 先進垂直連續酸性電鍍銅技術

COPPER GLEAM™ HV-101 and HVS-202 Electrolytic Copper

HV-101 exhibits excellent plating performance and advantage for production. High plating efficiency helps to increase productivity and reduce plating cost.

HVS-202 is developed from the basis of HV-101 for insoluble anode plating system, which provides similar performance but higher operation current density.

HV-101具備優越的電鍍特性與量產的優勢。高電鍍效率有助於提高產能並減少電鍍成本。

HV-202為基於HV-101的基礎所發展出來的產品，以應用於搭配不溶解性陽極的電鍍系統。可提供相近於HV-101的優越表現, 且可使用於較高的電流密度下。

Features and Benefits 特性及優點

- Excellent throwing power on through hole and microvia over high current density
  在高電流下仍具備優越的通孔與盲孔貫孔能力
- Superior panel plating distribution
  良好的電鍍均勻度
- Superior leveling performance for panel surface and rough through hole
  於表面與孔內有良好的整平效果
- Round bottom phenomenon on microvia
  於盲孔底部有圓孔效果
- Good thermal reliability
  優異的耐熱信賴度

1.6 mm thickness, 0.3 mm diameter

100 µm depth,150 µm width

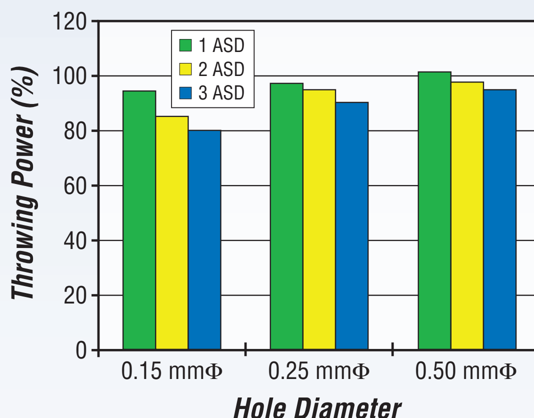

Fig. 1 TP performance on different through hole

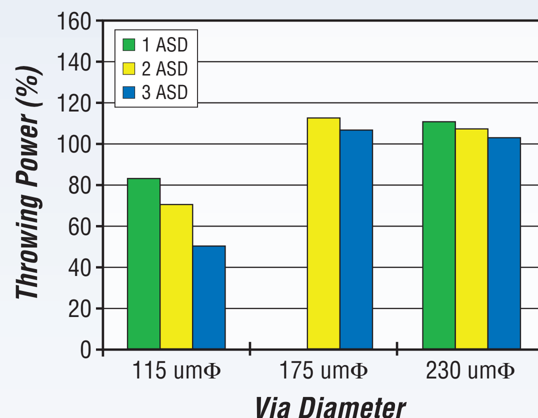

Fig. 2 TP performance on different microvia diameter and current density

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